PRODUCT: CERAMIC DISC CAPA SAFETY RECOGNIZE	
TYPE: AH SERIES	
CUSTOMER:	
DOC. NO.: POE-D10-00-E-27	
Ver.: 27	
APPROVED BY CUSTOM	ER
VENDOR :	
	HITANO ENTERPRISE CORP. ®
HITANO ENTERPRISE CORP. 7F-7, NO. 3, WU CHUAN 1ST ROAD, NEW TAIPEI INDUSTRIAL PARK, NEW TAIPEI CITY, TAIWAN, R.O.C. TEL: +886 2 2299 1331 (REP.)	

HI'	<b>FANO</b>

ENTERPRISE CORP. ®

POE-D10-00-E-27

CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Ver: 27

Page: 2/ 21

		Record of change	
Date	Version	Description	page
2008.6.3	1	1. D22-00-E-01(before) $\rightarrow$ POE-D10-00-E-01(1st edition)	
2008.8.22	2	1. Complete lead code	21
		2. Add last SAP code "H" for halogen and Pb free, epoxy resin	3
2008.12.12	3	1. Complete the 13th to 17th codes of SAP P/N.	4-5
2009.7.8	4	2. Page layout adjustment.	
2009.7.8	4	<ol> <li>1 Change PSA &amp; POE logo to Walsin &amp; POE logo.</li> <li>2. Complete Marking statement.</li> </ol>	10
		<ol> <li>Revised standard NO. of SEV, SEMKO, FIMKO, NEMKO, DEMKO and KEMA.</li> </ol>	10
		4. Revised recognized NO. of FIMKO, NEMKO, DEMKO and KEMA.	
2009.9.14	5	1. H0: 18.0+2.0/-1.5 revised to 18.0+2.0/-0	9
		2. "Protrusion length": "+0.5to-1.0" revised to "2.0max (Or the end of lead wire may	9
		be inside the tape.)"	10
2000 12 24	6	3. 3. Add "250V~" under the "UL" mark according to the product's marking.	10
2009.12.24	6	1. Marking 2. Correct X1 of recognized No. by KTI	10 11
		<ol> <li>Correct X1 of recognized No by KTL.</li> <li>Revised the Figure of impulse voltage test(Item 7.3.14) according to the standard</li> </ol>	11
		IEC 60384-14 ed.3	14
		4. Add "1AH" code for Y1:400V marking type.	4
2011.1.11	7	1. Review SAP P/N about diameter code: YU*AH561K100*→YU*AH561K080*	6
		2. Delete "AT" taping type.	4,5,8,9
		3. Add test item "Temperature Cycle".	14
2011 5 12		4. Add item 10 "Drawing of internal structure and material list"	19
2011.5.12	8	<ol> <li>Review the safety standards approval and recognized no.</li> <li>Delete "old P/N"</li> </ol>	10 5~6
		<ol> <li>Detete old 1/N</li> <li>Add the special marking for P/N:YP*AH102K100</li> </ol>	3~0 9
2012.1.30	9	<ol> <li>Review the approval rated voltage of UL and the marking.</li> </ol>	8~9
2012/4/6	10	<ol> <li>In order to improve the traceability of the product, change the date code on</li> </ol>	8
2012/ 1/0	10	capacitor body, new date code can trace back to production "Lot No."	Ű
		1. Review the Lead diameter $\varphi$ from 0.60 +0.1/-0.05mm to 0.55+/-0.05mm	5,6,7
		2. Add"3.1Norminal parts&3.2 special for surge parts" for "3. Part	6
		numbering/T.C/Capacitance/ Tolerance/Diameter"	
2012/5/12	1.1	3. In order the customer to know the round time of manufacture, change the date code	8
2013/5/13	11	<ul><li>on capacitor body, new date code can know the month of manufacture.</li><li>4. Delete "No marked with "_" stand for Pb free".</li></ul>	
		5. Delete "When the TCC is $\overline{Y5V}(YV)$ , there is a "F" between the "AH" and	8
		capacitance code."	8
		6. Review the Solderability time from $2 \pm 0.5$ s to $5 \pm 0.5$ s	11
		1. Review the "Manufactured Date" to "Products ID" on the marking page	8
2013/10/16	12	<sup>2.</sup> Delete "The marking can be printed on either one side or two side of coating body. and add "for SAP" part number 10-11 digits, ≤ 07 products to two sides and "for SAP part number 11-12 digits ≥ '08 products to one side.	
2013/10/10	12	SAP part number $11-12$ digits $\ge$ 08 products to one side.	8
		1. Review the size of SL*AH820J*** from 080 to be 090.	6 7
		<ol> <li>Review the terminal position of the lead wire.</li> <li>Review the product of ID, add the code "D" for the products of Dongguan Walsin</li> </ol>	8
		Technology Electronics Co., Ltd.	0
2014/11/5	13	<ol> <li>Review the Operating Temperature Range, from "-25 to +125°C" to be "-40 to</li> </ol>	11
		+125°C".	
		5. Review the minimum packing quantity of taping code AM.	15
		6. Review the low temperature range from $-25^{\circ}$ C to $-40^{\circ}$ C for temperature cycle test.	13
2016/1/27	1 /	1. Review the Available lead code of Lead Configuration	5
2016/1/27	14	2. Add the SAP P/N :YU*AH681M*. 2. Boylight dandard NO, of VDE, SEW SEMKO, EIMKO, NEMKO and DEMKO	6 9
		<ol> <li>Revised standard NO. of VDE, SEV, SEMKO, FIMKO, NEMKO and DEMKO.</li> <li>Delete 6 Pf~10 Pf for P/N CH*AH***D06 * *, 12 Pf for P/N CH*AH120J06 * *</li> </ol>	-
2016/5/2	15	and 15 Pf~27 Pf for P/N CH*AH***J07 * *.	6
2016/5/3	15	2. Add 10 Pf&12 Pf for P/N SL*AH***J06 * *	6
		1	U

#### **Record of change**

ENTERPRISE CORP. ®

POE-D10-00-E-27

CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Ver: 27

Page: 3/21

Date	Version	Description	page
2016/11/3	16	1. Delete "CH" series.	4,6,10~13,18
2017/2/16	17	1. Add "C" code Pitch 12.5mm.	4,5
2017/3/10	18	1. Revise CQC Standard No.	10
2018/8/11	19	1. Revised standard NO. of VDE, SEV, SEMKO, FIMKO, NEMKO and DEMKO.	10
2019/2/25	20	1. Delete "3.2 Special design parts" for surge withstanding	6
2019/4/24	21	<ol> <li>"Protrusion length": "2.0max (Or the end of lead wire may be inside the tape.)" revised to "+0.5to-1.0 (Or the end of lead wire may be inside the tape.)"</li> <li>Add "AS"&amp; "AT" taping type.</li> <li>Add "Soldering Recommendation"</li> </ol>	7~8 8 19
2019/12/11	22	<ol> <li>Review the Available lead code of Lead Configuration</li> <li>Add "8.3 Label samples"</li> </ol>	5 15
2021/9/9	23	1. Delete Walsin & POE logo.	1
2022/4/18	24	<ol> <li>Add Applied voltage in 9.1 Caution (Rating):</li> <li>Add 9.3.4 List of substances that affect the insulation strength of coating</li> </ol>	17 19
2023/5/10	25	1. Add the Special marking for P/N: YU1AH471M*/ YU1AH561M* /YU1AH681M*.	9
2023/5/26	26	1. Revised recognized No. of SEMKO and FIMKO.	10
2023/9/25	27	1. Review the bulk packing quantity of the code of 14th to15th $\ge 12$	15

# **Table of Contents**

No.	Item	Page
1	Part number for SAP system	4
2	Mechanical	5
3	Part numbering/T.C/Capacitance/ Tolerance/Diameter	6
4	Taping Format	7~8
5	Marking	9
6	Scope	10
7	Specification and test method	11~14
8	Packing specification	15
9	Notices	16~19
10	Soldering Recommendation	20
11	Drawing of Internal Structure and material list	21

#### Record of change (continue)

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 4/ 21

#### 1. Part number for SAP system:

(Ex.)	YU	0	AH	472	M	13	0	L	20	C	0	H
	(1)	(2)-1	(2)-1	(3)	(4)	(5)	(6)	(7)	(8)	(9)	(10)	(11)

(1)Temperature characteristic (identified code)

CODE	Temperature characteristic	Cap. Change		
SL	SL	-1000~+350ppm/°C (+20°C~+85°C)		
YP Y5P		$\pm 10\%$		
YU	Y5U	-55% to +20%		
YV	Y5V	-80% ~ +30%		

(2)-1 Rated voltage(identified by 1-figure code)  $: 0 = X1:400V \sim /Y1:250V \sim$ ,

1=X1:400V~/Y1:400V~ (2)-2 Type(identified by 2-figure code) : AH

(3)Capacitance (identified by 3-figure code):EX.221=220pF

(4)Capacitance tolerance (identified by code): J:±5%,K:±10%,M:±20%

(5) Nominal body diameter dimension (identified by 2-figure code) : 06--Dmax7.0mm, 07--Dmax8.0mm...

- (6) Internal code: 0--Normal, other code--Special control
- (7) Lead Style : Refer to "2. Mechanical".

(8) Packing mode and lead length (identified by 2-figure code)

Taping Code	Description		
AM	Ammo box and product pitch : 25.4 mm		
AS	mmo box and product pitch : 15.0 mm		
	(Only for the SAP part number 11-12 digits $\leq 10$ )		
AT	Ammo box and product pitch : 30.0 mm		

Bulk Code	Description				
03	Lead length : 3.0mm				
3E	Lead length : 3.5mm				
04	Lead length : 4.0mm				
4E	Lead length : 4.5mm				
20	Lead length : 20mm				

#### (9) Length tolerance

Code	Description		
A	±0.5 mm (only for kink lead type)	Short lead	
В	±1.0 mm	Short lead	
C	Min.	Long lead	
D	Taping special purpose	Taping	

#### (10) Pitch

Code	Description	
0	10±1 mm	
А	10±0.5 mm	
С	12.5± 0.8 mm	

(11) Epoxy Resin Code

Code	Description
В	Halogen and Pb free, epoxy resin.
Н	Halogen and Fo nee, epoxy tesm.

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 5/ 21

#### 2. Mechanical:

Encapsulation : Epoxy resin, flammability UL94 V-0 Available lead code (unit: mm):

Lead type	SAP P/N (13-17)digits	Pitch (F)	Lead Length (L)	Packing	Lead Configuration
	L03B0	$10\pm1.0$	$3.0 \pm 1.0$		
	L4EB0	$10 \pm 1.0$	4.5 ± 1.0		D max. T max.
	L05B0	$10 \pm 1.0$	5.0 ± 1.0		
	L03BC	$12.5\pm0.8$	3.0 ± 1.0	Bulk	
Lead style : L or B Type L or B	L4EBC	$12.5\pm0.8$	4.5 ± 1.0		L≧20mm
	L05BC	$12.5\pm0.8$	$5.0 \pm 1.0$		
Straight lead	L20C0	$10 \pm 1.0$	20 min.		
	L20CC	$12.5\pm0.8$	20 min.		L For L<20mm
	BAMD0	$10 \pm 1.0$			d+++
	BASD0	$10 \pm 1.0$	Refer to "4. Taping format"	Tap. Ammo	_
	BATD0	10 ± 1.0	Iormat	-	
	G03B0	$10 \pm 1.0$	3.0 ± 1.0		D max. T max.
	G4EB0	10 ± 1.0	4.5 ± 1.0	Bulk	
Lead style : G Type G	G05B0	10 ± 1.0	5.0 ± 1.0		
Straight lead	GAMD0	10 ± 1.0			
	GASD0	10 ± 1.0	Refer to "4. Taping format"		
	GATD0	$10 \pm 1.0$		Tap. Ammo	
	D03A0	10 ± 1.0	3.0 ± 0.5		
	D3EA0	$10 \pm 1.0$	3.5 ± 0.5		
	D04A0	$10 \pm 1.0$	4.0 ± 0.5	Bulk	
Lead style : D Type D	D03AC	$12.5\pm0.8$	3.0 ± 0.5	DUIK	
	D3EAC	$12.5\pm0.8$	3.5 ± 0.5		
Vertical kink lead	D04AC	$12.5\pm0.8$	4.0 ± 0.5		
icuu	DAMD0	10 ± 1.0			╠╾╒╶┽ <u>╢</u> ┠ <u></u> ┤ <u></u> Т <del>╡</del>
	DASD0	$10 \pm 1.0$	Refer to "4. Taping format"	Tap. Ammo	Ød-l+ <u> </u>
	DATD0	$10 \pm 1.0$	Torritut		plane 1 (anno 1 million - family)
	X03A0	10 ± 1.0	$3.0 \pm 0.5$		D max. T max.
	X3EA0	$10 \pm 1.0$	3.5 ± 0.5		
	X04A0	$10 \pm 1.0$	4.0 ± 0.5		
Lead style : X	X05B0	10 ± 1.0	5.0 ± 1.0	Bulk	
Type X	X03AC	$12.5\pm0.8$	3.0 ± 0.5	Duik	
Outside kink lead	X3EAC	$12.5\pm0.8$	3.5 ± 0.5	]	
	X04AC	$12.5\pm0.8$	$4.0 \pm 0.5$		20 max
	X05BC	$12.5\pm0.8$	5.0 ± 1.0		
	XAMD0	10 ± 1.0	Refer to "4. Taping	<sup>g</sup> Tap. Ammo	
	XATD0	$10 \pm 1.0$	format"		

\* Lead diameter  $\Phi$ d: 0.55 +/-0.05mm

\*e (Coating extension on leads): 3.0mm Max for straight lead style, not exceed the kink for kink lead.

HITANO ENTERPRISE CORP. ®

CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Ver: 27

Page: 6/ 21

## 3. Part numbering/T.C/Capacitance/ Tolerance/Diameter :

			-		Dimen	sion (unit:mm)	
SAP P/N	T.C.	Capacitance(pF)	Tolerance	D(max.)	T(max.)	F	Φd
SL*AH***J060*		10,12,15,18,20,22,24, 27,30,33, 36, 39(pF)		7.0			
SL*AH***J070*	SL*	47,50,51, 56,62(pF)	$\pm 5\%$	8.0			
SL*AH***J080*		68,75(pF)		9.0			
SL*AH***J090*		82,100(pF)		10.0			
YP*AH101K060*		100 pF		7.0			
YP*AH151K060*		150 pF		7.0	5.0	10±1	0.55+/-0.05
YP*AH221K060*		220 pF		7.0			
YP*AH331K060*	Y5P	330 pF	+ 100/	7.0			
YP*AH471K070*	1 JF	470 pF	±10%	8.0			
YP*AH561K080*		560 pF		9.0			
YP*AH681K080*		680 pF		9.0			
YP*AH102K100*		1000 pF		11.0			
YU*AH471M060*		470 pF		7.0			
YU*AH561M060*		560 pF		7.0			
YU*AH681M060*		680 pF		7.0			
YU*AH102M070*		1000 pF		8.0			
YU*AH152M080*	Y5U	1500 pF		9.0	5.0		
YU*AH222M090*		2200 pF		10.0			
YU*AH332M110*		3300 pF	±20%	12.0		10±1	0.55+/-0.05
YU*AH392M120*		3900 pF		13.0		10±1	0.55+7-0.05
YU*AH472M130*		4700 pF		14.0			
YV*AH102M060*		1000pF		7.0			
YV*AH152M070*		1500pF		8.0			
YV*AH222M080*	Y5V	2200pF		9.0	5.5		
YV*AH332M100*		3300pF		11.0			
YV*AH472M110*		4700pF		12.0			

• The minimum thickness of coating (reinforced insulation) is 0.4mm.

HITANO ENTERPRISE CORP.			POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED AH SERIES	),	Ver: 27	Page: 7/ 21

#### 4. Taping Format:



™ *B*	"D*	*X* *G*		
POE Part Number		*BAMD0 / *DAMD0 / *XAMD0/ *GAMD0		
Item	Symbol	Dimensions(mm)		
Pitch of component	Р	25.4 ± 2		
Pitch of sprocket	P0	12.7 ± 0.3		
Lead spacing	F	10.0 ± 1.0		
Length from hole center to component center	P2	12.7 ± 1.5		
Length from hole center to lead	P1	7.7 ± 1.5		
Body diameter	D	See the "3. Part numbering/T.C/Capacitance/ Tolerance/Diameter"		
Deviation along tape, left or right	$\triangle$ S	0 ± 2.0		
Carrier tape width	W	18.0 +1/ -0.5		
Position of sprocket hole	W1	9.0 ± 0.5		
Lead distance between the kink and center of sprocket hole	H0	18.0+2.0/-0 (For: *DAMD0 & *XAMD0 & *GAMD0)		
Lead distance between the bottom of body and the center of sprocket hole	Н	20.0+1.5/-1.0 (For: *BAMD0)		
Length from the terminal of the lead wire to the edge of carrier tape	ł	+0.5 to -1.0 (or the end of lead wire may be inside the hole-down tape.)		
Diameter of sprocket hole	D0	4.0 ± 0.2		
Lead diameter	φd	0.55 ±0.05		
Total tape thickness	t1	0.6 ± 0.3		
Total thickness, tape and lead wire	t2	1.5 max.		
Deviation compare tone	$\triangle$ h1	2.0 max.		
Deviation across tape	$\triangle$ h2	2.0 max		
Portion to cut in case of defect	L	11.0 max.		
Hole-down tape width	W0	8.0 min		
Hole-down tape distortion	W2	$1.5 \pm 1.5$		
Coating extension on leads	e	3.0mm max for straight lead style; Not exceed the kink leads for kink lead.		
Body thickness	Т	See the "3. Part numbering/T.C/Capacitance/ Tolerance/Diameter"		



•15mm pitch/lead spacing 10.0mm taping Lead Code: \*BASD0 & \*DASD0 & \*GASD0

#### • 30mm pitch/lead spacing 10.0mm taping Lead Code: \*BATD0 & \*DATD0 & \*XATD0 & \*GATD0













POE Part Number		*BASD0/*DASD0/*GASD0	*BATD0/*DATD0 /*GATD0/*XATD0	
Item	Symbol	Dimensions(mm)		
Pitch of component	Р	15.0±1	30.0 ± 2	
Pitch of sprocket	P0	1	5.0±0.3	
Lead spacing	F	1	$0.0{\pm}1.0$	
Body diameter	D	See the "3. Part numbering/T.C	C/Capacitance/ Tolerance/Diameter"	
Deviation along tape, left or right	$\triangle$ S	(	$0 \pm 2.0$	
Carrier tape width	W	18.0	0 +1/ -0.5	
Position of sprocket hole	W1	9.	.0 ± 0.5	
Lead distance between the kink and center of sprocket hole	Н0	18.0 +2.0/-0 (For: *DASD0 & *GASD0)	18.0 +2.0/-0 (For: *DATD0 & *GATD0 & *XATD0)	
Lead distance between the bottom of body and the center of sprocket hole	Н	20.0+1.5/-1.0 (For: *BASD0)	20.0+1.5/-1.0 (For: *BATD0)	
Length from the terminal of the lead wire to the edge of carrier tape	l	+0.5 to -1.0 (or the end of lead wire may be inside the hole- tape.)		
Diameter of sprocket hole	D0	4.0 ± 0.2		
Lead diameter	φd	0.55 ±0.05		
Total tape thickness	t1	0.	.6 ± 0.3	
Total thickness, tape and lead wire	t2	1	.5 max.	
Deviation across tape	$\triangle$ h1/ $\triangle$ h2	2.0 max.		
Portion to cut in case of defect	L	11.0 max.		
Hole-down tape width	W0	8.0 min		
Hole-down tape distortion	W2	1.	.5 ± 1.5	
Coating extension on leads	e	3.0 max for straight lead style; Not exceed the kink leads for kin lead.		
Body thickness	Т	See the "3. Part numbering/T.C/Capacitance/ Tolerance/Diamete		

ød

ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 9/ 21

## 5. Marking:

1.Type Designation	AH		
2.Nominal Capacitance	Identified by 3-Figure Code. Ex. $47pF \rightarrow "47"$ ,	470pF <b>→</b> "471"	
3.Capacitance Tolerance	J:±5%,K:±10%,M:±20%		
4.Company Name Code(Trade mark)	UK		
5. Products ID	1:2021 2:2022 3:2023 Manufactory: C:Pan overseas (Guangzhou) (Guangzhou) (For the last code "H" and "B" of SAP P/N) (Individual Manufactory: (For the last code "H" and "B" of SAP P/N)	st 4 digits of lot no. specification code anufacture month: January Feruary September October November December	
6.Approved Monogram:	IEC 60384-14		
(1) VDE approval mark	Class Code : X1 : 400V~ , Y1 : 250	V~ or 400V~	
(2) UL approval mark	<b>FL</b> (6) DEMKO approval mark	D	
(3) CSA approval mark	(7) FIMKO approval mark		
(4) SEMKO approval mark	(8) SEV approval mark	( <del>t</del> )	
(5) NEMKO approval mark	(9) CQC approval mark		
Normal	marking Specia	al marking	
Two sides ( for SAPpart number 10-11 digits ≤ "07 " products )	(for SAP part number 10-11 (For *1AH4)	`wo sides 71M* / *1AH561M <sup>;</sup> AH681M*)	
$\begin{array}{c} K \\ AH101K \\ \mathfrak{G} \\ \mathfrak{G} \\ \mathfrak{F} \\ \mathfrak{F}$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	A X1Y1 2 <u>C</u> 61234	
<ul> <li>* Marking by the laser.</li> <li>*" <u>C</u>": Marked with code " _ " state the second structure of the second structure o</li></ul>	and for Halogen and Pb free epoxy resin. de, it is added under the lot no.		

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 10/ 21

#### 6. Scope:

THIS SPECIFICATION APPLIES TO CERAMIC INSULATED CAPACITORS DISK TYPE USED IN ELECTRONIC EQUIPMENT.

#### 6.1 Applicable safety standard

This specification applies to the VDE, SEV, SEMKO, FIMKO, NEMKO, DEMKO, KTL, UL, CSA approved ceramic capacitors disc type for antenna coupling, line-by-pass and across-the-line. X1, Y1 capacitor based on IEC60384-14. "UL, CSA recognized capacitor for across-the-line, line-by-pass" and antenna-isolation.

6.2 Safety standards	s approval and	l recognized no.
----------------------	----------------	------------------

Safety Standard	Standard No.	Subclass	w.v.	Recognized No.
UL	ANSI/UL 60384-14:2013	X1	400VAC	E146544
		Y1	250VAC/400VAC	
CSA	IEC60384-14 (ed.4) 2013	X1 Y1	400VAC 250VAC/400VAC	2347971
	EN 60384-14:2013/A1:2016			
VDE	IEC 6.384-14:2013	X1	400VAC	40001804
(ENEC)	IEC 6.384-14:2013/AMD1:2016	Y1	250VAC/400VAC	10001001
ENEC		X1	400VAC	ENEC-01966
(DEMKO)	EN 60384-14	Y1	250VAC/400VAC	
		X1	400VAC	01.0554
SEV	EN 60384-14:2013 + A1:16	Y1	250VAC/400VAC	21.0554
SEMKO	EN 60384-14:2013+A1	X1	400VAC	SE-S-1811992R1
SEMIKU		Y1	250VAC/400VAC	SE-S-1011992K1
FIMKO	EN (0294 14/2012 - A1/16	X1	400VAC	FI/41697
FINKU	EN 60384-14:2013 + A1:16	Y1	250VAC/400VAC	FI/41097
NEMKO	EN 00004 44:0040:44	X1	400VAC	No. P18222946
NEWINO	EN 60384-14:2013;A1	Y1	250VAC/400VAC	NO. P18222940
DEMKO	EN 60384-14:2013/A1:2016	X1	400VAC	D-07609
DEWIKU	EN 60384-14:2013	Y1	250VAC/400VAC	D-07009
COC	IEC60384-14:2013+AMDI:2016	X1:400VAC/Y1:400VAC		CQC03001003673
CQC	GB/T6346.14-2015	X1:400	OVAC/Y1:250VAC	CQC11001055510
	KC60384-1(2015-09)	X1	400VAC	SU03065-14004A
KTL	KC60384-14(2015-09)	Y1	250VAC	SU03065-14005A
	IEC 60384-14(ed.3)	Y1	400VAC	SU03065-14006A

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 11/21

#### 7. Specification and test method:

- 7.1 Operating Temperature Range: -40 to +125 °C
- 7.2 Test condition:

Test and measurement shall be made at the standard condition. (temperature  $15 \sim 35^{\circ}$ C, relative humidity  $45 \sim 75\%$  and atmospheric pressure  $860 \sim 1060$  hpa). Unless otherwise specified herein.

If doubt occurred on the value of measurement, and measurement was requested by customer capacitors shall be measured at the reference condition. (temperature  $20\pm2$ °Cor25  $\pm$  2°C, relative humidity 60~70% and atmospheric pressure 860~1060hpa.)

#### 7.3 Performance:

No	It	ems	Performance	Testing method		
7.3.1	And di	earance mension	No visible defect, and dimensions are within specified range.	The capacitor should be visually inspected for evidence of defect. Dimensions should be measured with slide calipers.		
7.3.2	Ma	rking	To be easily legible.	The capacitor should be visually inspected.		
		Between terminals	No failure.	The capacitors shall not be damage when AC4000V (rms.) are applied between the lead wires for 60sec. (Charge/Discharge current $\leq$ 50mA.)		
7.3.3	Dielectric Strength	Body Insulation	No failure.	First, the terminals of the capacitor should be connected together. Then, a metal foil should be closely wrapped around the body of the capacitor to the distance of about 3 to 6mm from each terminal. Then, the capacitor should be inserted into a container filled with metal balls of about 1mm diameter. Finally, AC4000V (r.m.s.)<50/60Hz> is applied for 60 s between the capacitor lead wires and metal balls. (Charge/Discharge current $\leq$ 50mA.)		
7.3.4	Insulation Resistance	Between terminals	$10000M\Omega$ or more.	The insulation resistance shall be measured with DC500±50V within 60±5sec of charging.		
7.3.5	Capa	acitance	Within specified tolerance.	<ul> <li>Y5P&amp;Y5U&amp;Y5V: The capacitance should be measured at 20°C with 1±0.2kHz and 1.0Vrmax.</li> <li>SL: The capacitance shall be measured at 25°C with 1MHz±20% and1.0Vrms</li> </ul>		
7.3.6	Diss	ipation tanδ) or Q	Y5P $\cdot$ Y5U : D.F. $\leq 2.5\%$ Y5V : D.F. $\leq 5.0\%$ SL :30pF&above: $\geq 1000$ Below 30PF: $\geq 400+20\times C$			
7.3.7		cteristic	Char.         Capacitance Change           Y5P         Within ±10%	The capacitance measurement shall be made at each step specified in Table 1.		
			Y5U Within $\pm \begin{array}{c} 20\\55 \end{array}$ %	Step         1         2         3         4         5		
			Y5V Within -80~+30% -1000~+350	Temp.(°C) +20±2 -25±2 +20±2 +85±2 +20±2		
			SL ppm/°C (+20°C~+85°C)	Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour, then placed at ¾ 1room condition for 24±2hours before measurements.		
7.3.8	Solderability	of Leads	Lead wire should be soldered with uniform coating on the axial direction over 3/4 of the cumferential direction.	The lead wire of capacitor should be dipped into molten solder for $5 \pm 0.5$ sec. The depth of immersion is up to about 1.5 to 2.0 mm from the root of lead wires. Temp. of solder : Lead Free Solder (Sn-3Ag-0.5Cu) 245±5°C		

 $\label{eq:condition} \mbox{``room condition'' temperature : 15~35°C, humidity : 45~75\%, atmospheric pressure : 86~106 kPa$ 

\* "C" expresses nominal capacitance value (pF).

# HITANO

 POE-D10-00-E-27

#### CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Ver: 27 Page: 12/ 21

No	Iten	ns	Performance	Testing method
		Tensile	Lead wire shall not cut off capacitor shall not be broken.	As shown in the figure at right, fix the body of the capacitor and apply a tensile weight gradually to each lead wire in the radial direction of the capacitor up to 10N and keep it for 10±1 sec.
7.3.9	Robustness of Terminations	Bending	Lead wire shall not cut off. Capacitor shall not be broken.	With the termination in its normal position, the specimen is held by its body in such a manner that the axis of the termination is vertical; a mass applying a force of 5N is then suspended from the end of the termination. The body of the specimen is then inclined, within a period of 2 to 3sec, through an angle of approximately 90° in the vertical plane and then returned to its initial position over the same period of time; this operation constitutes one bend. One bend immediately followed by a second bend in the opposite direction.
		Appearance	No marked defect.	As shown in figure, the lead wires should be immersed in
		I.R.	1000 M $\Omega$ min.	solder of $350 \pm 10$ °C or $260 \pm 5$ °C up to 1.5 to 2.0 mm from the root of terminal for $3.5 \pm 0.5$ sec ( $10 \pm 1$ sec. for $260 \pm 5$ °C ).
		Dielectric Strength	Per item7.3. 3	Thermal Capecitar Screen
7.3.10	Soldering Effect (Non-Preheat)	Capacitance Change	Y5P,Y5U,Y5V : Within ±10 % SL : Within ±2.5 % or ±0.25pF,Whichever is large.	Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at <sup>*1</sup> room condition for 24±2hours before initial measurements. Post-treatment: Capacitor shall be stored for 1 to 2hours at <sup>*1</sup> room condition.
		Appearance	No marked defect.	First the capacitor should be stored at $120+0/-5$ °C for 60 +0/-5 sec. Then , as in figure , the lead wires should be immersed solder of $260+0/-5$ °C up to 1.5 to 2.0 mm from the root of terminal for 7.5+0/-1 sec. Thermal Capacitor Screen 1.5 to 2.0 mm
7.3.11	Soldering	I.R.	1000 MΩ min.	
7.3.11	Effect (On-Preheat)	Dielectric Strength	Per item 7.3.3	Solder
		Capacitance Change	Y5P,Y5U,Y5V : Within±10 % SL : Within±2.5% or ±0.25pF,Whichever is large.	Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at <sup>*1</sup> room condition for 24±2hours before initial measurements. Post-treatment: Capacitor shall be stored for 1 to 2hours at <sup>*1</sup> room condition.

<sup>™</sup> "room condition" temperature : 15~35°C, humidity : 45~75%, atmospheric pressure : 86~106kPa

\* "C" expresses nominal capacitance value (pF).

HITANO

•

POE-D10-00-E-27

#### CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Ver: 27

Page: 13/ 21

No	Iten	ns	Performance	Testing method
7.3.12	Humidity (Under steady State)	Capacitance Change	No marked defect. Y5P: Within $\pm 10\%$ Y5U: Within $\pm 20\%$ Y5V: Within $\pm 30\%$ SL: Within $\pm 3.5\%$ or $\pm 0.25 pF$ , Whichever is large. Y5P, Y5U: 5.0% max.	Set the capacitor for $500\pm12$ hours at $40\pm2$ °C in 90 to 95% relative humidity. Then capacitor shall be stored for 1 to 2 hours at <sup>** 1</sup> room condition. Pre-treatment: Capacitor shall be stored at $125\pm2$ °C for 1hour.then placed at <sup>**1</sup> room condition for $24\pm2$ hours.
		D.F. Q	Y5V : 7.5% max. SL : Q≧100+10×C/3 (C<30pF)	Post-treatment: Capacitor shall be stored for 1 to 2hours at <sup>**1</sup> room condition.
7.3.13	Humidity Loading	I.R.	$Q \ge 200 (C \ge 30 \text{pF})$ Y5P&Y5U&Y5V : 3000MΩ min. SL : 1000MΩ min.	Apply the rated voltage for $500\pm12$ hours at $40\pm2$ °C in 90 to 95% relative humidity Pre-treatment: Capacitor shall be stored at $125\pm2$ °C for 1hour.then placed at <sup>**1</sup> room condition for 24±2hours. Post-treatment:
		Dielectric Strength	Per Item 7.3.3	Capacitor shall be stored for 1 to 2hours at <sup>**1</sup> room condition.
		Appearance	No marked defect.	Impulse Voltage Each individual capacitor shall be subjected to 8kV
		Capacitance Change	Y5P&Y5U&Y5V : Within ±20% SL : Within±3% or ±0.3pF,Whichever is large.	impulses for three times. After the capacitors are applied to life test. $V_{P}$ $U_{OR}$ $\overline{\underbrace{Cx}  tr}  M \\ \underline{(VF)}  \underline{(VS)}  \underline{(VS)}$
		I.R.	3000MΩ min. SL: 1000MΩ min.	Upp 0.5%p 0.5%p Upp 0.5%p
7.3.14	Life	Dielectric Strength	Per Item 7.3 3	Time The specimen capacitors are placed in a circulating air oven for a period of 1000 hours. The air in the oven is maintained at a temperature of 125±3°C. Throughout the test, the capacitors are subjected to an AC425Vrms.(for 0AH type) or AC680Vrms.(for 1AH type) alternating voltage of mains frequency. Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at <sup>*1</sup> room condition for 24±2hours. Post-treatment: Capacitor shall be stored for 1 to 2hours at <sup>*1</sup> room condition.

<sup>∗</sup> "room condition" temperature : 15~35°C, humidity : 45~75%, atmospheric pressure : 86~106kPa

\* "C" expresses nominal capacitance value (pF

HITANO ENTERPRISE CORP. ®

POE-D10-00-E-27

#### CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES

Page: 14/21

Ver: 27

No		Items	Performance	Testing method
7.3.15		Active nmability	The cheesecloth shall not be on fire.	The specimens shall be individually wrapped in at least one but more than two complete layers of cheesecloth. The specimens shall be subjected to 20 discharges. The interval between successive discharges shall be 5 sec. The UAC shall be maintained for 2 min after the last discharge. I = I = I = I = I = I = I = I = I = I =
7.3.16	Passive	Flammability	The burning time shall not be exceeded the time 30 sec. The tissue paper shall not ignite.	The capacitor under test shall be held in the position which best promotes burning. Each specimen shall only be exposed once to flame. Time of exposure to flame: 30sec. Length of flame : 12±1mm Gas burner : Length 35mm min. Inside Dia. : 0.5±0.1mm Outside Dia. : 0.9mm max. Gas : Butane gas Purity 95% min.
7.3.17	Temperat ure Cycle	AppearanceChar.Cap.ChangeSL $\leq \pm 5\%$ Y5P $\leq \pm 10\%$ Y5U $\leq \pm 20\%$	No marked defect $DF/Q$ $Q \ge 275+5/2C (C < 30pF)$ $Q \ge 350 (C \ge 30pF)$ $DF \le 5.0\%$ $DF \le 7.5\%$	The capacitor should be subjected to 5 temperature cycles, <Temperature Cycle time: 5cycles> $\hline Step Temperature(^{\circ}C) Time(min)$ 1 -40+0/-3 30 2 Room temp. 3 3 125+3/-0 30 4 Room temp. 3 Pre-treatment: Capacitor shall be stored at 125±2°C for 1hour.then placed at % 1room condition for 24±2hours.
		IR Dielectric strength	3000MΩ min. Per Item 7.3.3	Post-treatment: Capacitor shall be stored for 1 to 2hours at %1room condition.

 $\label{eq:condition} \mbox{``room condition'' temperature : 15~35°C, humidity : 45~75\%, atmospheric pressure : 86~106 kPa$ 

% "C" expresses nominal capacitance value (pF).

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 15/ 21

#### 8. Packing Baggage :

#### 8.1 Packing size:



#### 8.2 Packing quantity:

Packing type	The code of 14th to15th in SAP P/N	MPQ (Kpcs/Box)	Remark
	AM (The size code $\leq$ 11)	1	F=10mm
Taping	AM (The size code $\geq$ 12)	0.5	(Code -17th"A" or "0")
	AM(Code -17th"C")	0.5	F=12.5mm
	AS	1	
	AT	0.5	

Packing type	Lead length	Size code of 10th to 11th in SAP P/N	MPQ (Kpcs/Bag)	Kpcs/Box
Long lead		06~12	0.5	1.5
D11-	$(L \ge 20 \text{mm})$	13	0.5	1
DUIK	Bulk Short lead (L < 20mm)	06~12	0.5	2
		13	0.5	1.5

#### 8.3 Label samples



HITANO ENTERPRISE CORP. • POE		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 16/ 21

#### 9. Notices:

#### 9.1 Caution (Rating):

(1). Operating Voltage

Be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range.

When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing this irregular voltage.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage
Positional measurement	V0-p		Vp-p

(2). Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

- (3). Test condition for withstanding Voltage
- I. Test Equipment

Test equipment for AC withstanding voltage shall be used with the performance of the wave similar to 50/60 Hz sine waves.

If the distorted sine wave or over load exceeding the specified voltage value is applied, the defective may be caused.

#### II. Voltage Applied Method

When the withstanding voltage is applied, capacitor's lead or terminal shall be firmly connected to the output of the withstanding voltage test equipment, and then the voltage shall be raised from near zero to the test voltage.

If the test voltage without the raise from near zero voltage would be applied directly to capacitor, test voltage should be applied with the \*zero cross. At the end of the test time, the test voltage shall be reduced to near zero, and then capacitor's lead or terminal shall be taken off the output of the withstanding voltage

test equipment.

If the test voltage without the raise from near zero voltage would be applied directly to capacitor, the surge voltage may arise, and therefore, the defective may be caused.



ZERO CROSS is the point where voltage sine wave pass 0V.- See the right figure.

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 17/ 21

#### III. Applied voltage

The voltages of Table shall be applied between the respective measuring points of 1 min

for qualification approval and periodic testing and for a period of not less than 1 s for lot-by-lot quality conformance testing, a voltage proof test such as Test C shall be carried out only for qualification approval tests and periodic tests;

Attention is drawn to the fact that repetition of the voltage proof test by the user may damage the capacitor. If repetition of the voltage proof test is made by the user, the applied voltage should not be greater than 66 % of the test voltage specified in Table .

#### Table – Voltage proof

Class	Range of rated voltages	Test A	Test B or Test C	
X1	≤1 000 V	4,3 <i>U</i> R (d.c.) c	2 <i>U</i> R + 1 500 V (a.c.) with a minimum of 2 000 V (a.c.) a	
Y1 ≤500 V 4 000 V (a.c.) 4 000 V (a.c.)				
a For Delta and T-connected capacitor units according to Figures 5b and 5c, the test voltage for terminals to case shall be the appropriate test voltage for the Y-capacitors.				

b The UR in this d.c. test is the rated a.c.voltage value.

Note:

Test A – Between terminations

Test B – Internal insulation

Test C – External insulation (applicable only to insulated capacitors in nonmetallic case or in insulated metal case)

Figure 5b – Delta by-pass capacitor (in metallic housing)

Figure 5c – Example of a T-connected by-pass capacitor (in non-metallic housing)





\*For capacitors with non-metallic housings, the earth connection is brought out as a separate termination as is shown in Figure 5c.

(4). Fail-Safe

When capacitor would be broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

# Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

HITANO ENTERPRISE CORP. • POE		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 18/ 21

#### 9.2 Caution (Storage and operating condition):

Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

"Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used."

#### 9.3 Caution (Soldering and Mounting):

9.3.1 Vibration and impact:

Do not expose a capacitor or its leads to excessive shock or vibration during use.

9.3.2 Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

9.3.3 Cleaning (ultrasonic cleaning):

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

Rinsing time:5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

"Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used. "

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 19/ 21

# 9.3.4 List of substances that affect the insulation strength of coating : **Epoxy resin solvent**

Category	Model		
Ketone	Acetone	Butanone	Cyclohexanone
Esters	Ethyl acetate	Dibutyl phthalate	
Chlorinated hydrocarbons	Dichloromethane		

#### **Epoxy resin thinner**

Epoxy resili tililler				
Category		Model		
		HK-66 (Alkyl glycidyl ether)		
	Simple function group	501 (Butyl glycidyl ether)		
		690 (Phenyl Glycidyl Ether )		
		AGE (C12-14A	Aliphatic Polyalcohol Glycidyl Ether)	
		692 (Benzyl Glycidyl Ether)		
Reactive diluentactivated thinner		D-678 (Neoper	tyl glycol diglycidyl ether)	
		622 (1,4-Butanediol diglycidyl ether)		
	Two functional groups	669 (Ethylene glycol diglycidyl ether)		
		X-632 (Polypropylene glycol diglycidyl ether)		
		X-652 (1,6-Hexadiol diglycidyl ether)		
		D-691Epoxypropane o-methylphenyl ether		
		Anhydrous	Toluene	
		ethanol		
		Ethyl acetate	Dimethylbenzene	
Non-activated thinn	ner	Dimethyl	Butyl acetate	
		formamide	,	
		Acetone	Styrene	
		Polyol	Benzyl alcohol	

Note: The above substances should not contact the coating of the product body, otherwise it will affect the insulation strength of the product

#### 9.4 Caution (Handling):

Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

"Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used."

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 20/ 21

#### 10. Soldering Recommendation:

#### **10.1 Wave Soldering Profile:**

- Temperature conditions of the flow is recommended as shown in the chart
- Must implement the pre-heat
- Maximum peak flow temperature is recommended  $265^{\circ}$ C
- Time "T" implement in the chart recommended within 20 sec. it temperature exceed 200°C
- Take care with the flow solder not to touch the capacitor body directly at mounting



#### Chart to show flow recommended temp

#### 10.2 Recommended Reworking Conditions with Soldering Iron:

- Temperature of iron-tip: 400 degrees C. max.
- Soldering iron wattage: 50W max.
- Soldering time: 3.5 sec. max.
- Distance from coating body: 2 mm (min.)

10.3 Reflow-Soldering : Lead Ceramic Cap. should not be soldered by reflow-soldering.

HITANO ENTERPRISE CORP.		POE-D10-00-E-27
CERAMIC DISC CAPACITOR SAFETY RECOGNIZED, AH SERIES	Ver: 27	Page: 21/21

1. Drawing of internal structure and material list:



### Remarks :

No.	Part name	Material	Model/Type	Component
1	Insulation Coating	Epoxy polymer	EF-150 PCE-300 ECP-357	Epoxy resin Pigment (Blue / UL 94 V-0) The minimum thickness of coating (reinforced insulation) is 0.4mm
2	Dielectric Element	Ceramic	SL/Y5P/Y5U/Y5V	SL: SrCO3/TiO2/Bi2O3/CaCO3 Y5P: BaTiO3/Bi2O3/SnO2/CeO2 Y5U: BaTiO3/ZrO2/ CaCO3 Y5V: BaTiO3/ WO3/ CeO2
3	Solder	Tin-silver	Sn96.5-Ag3-Cu0.5	Sn96.5-Ag3-Cu0.5
4	Electrodes	Ag	SP-160PL SP-260PL	Silver、Glass frit
5	Leads wire	Tinned copper clad steel wire	0.55±0.05mm	Substrate metal: Fe & Cu Surface plating: Sn 100%(3~7µm)